SDAS085B - APRIL 1982 - REVISED DECEMBER 1994

 Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

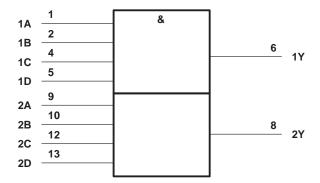
These devices contain two independent 4-input positive-AND gates. They perform the Boolean functions $Y = A \cdot B \cdot C \cdot D$ or $Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}$ in positive logic.

The SN54ALS21A and SN54AS21 are characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS21A and SN74AS21 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

		(000011	g,	
	INP	UTS		OUTPUT
Α	В	С	D	Y
Н	Н	Н	Н	Н
L	Х	Х	Х	L
Х	L	Х	Х	L
Х	Х	L	Х	L
Х	Х	Х	L	L

logic symbol[†]



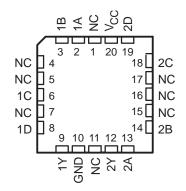
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54ALS21A, SN54AS21...J PACKAGE SN74ALS21A, SN74AS21...D OR N PACKAGE (TOP VIEW)

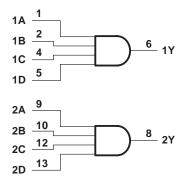
	(,	
1A [1B [NC [1C [1D [1Y [GND]	3 4 5	14 13 12 11 10 9 8] V _{CC}] 2D] 2C] NC] 2B] 2A] 2Y

SN54ALS21A, SN54AS21...FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram (positive logic)



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

	SN54ALS21A	
S	SN74ALS21A C)°C to 70°C
Storage temperature range		°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS21A		1A	SN	1A	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
$V_{ L}$	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-0.4			-0.4	mA
IOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS			1A	SN	74ALS2	1A	UNIT
PARAMETER	TESTC	UNDITIONS	MIN	TYP‡	MAX	MIN	typ‡	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lı = -18 mA			-1.5			-1.5	V
VOH	$V_{CC} = 4.5 V$ to 5.5 V,	I _{OH} = -0.4 mA	V _{CC} -2	2		V _{CC} -2	2		V
Net		$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
V _{OL}	$V_{CC} = 4.5 V$	I _{OL} = 8 mA					0.35	0.5	V
lj	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
Чн	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
١ _{IL}	$V_{CC} = 5.5 V,$	$V_{I} = 0.4 V$			-0.1			-0.1	mA
۱ ₀ §	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-20		-112	-30		-112	mA
Іссн	V _{CC} = 5.5 V,	V _I = 4.5 V		0.85	1.4		0.85	1.4	mA
ICCL	V _{CC} = 5.5 V,	$V_{I} = 0$		1.4	2.3		1.4	2.3	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

\$ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	то (оитрит)	CL RL T _A	= 50 pF = 500 Ω = MIN t	2, o MAX¶		UNIT
			SN54A MIN	MAX	SN74A	MAX	
^t PLH		V	4	18	4	15	20
^t PHL	A, B, C, or D	ſ	2	15	2	10	ns

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} Input voltage, V _I	
Operating free-air temperature range, T _A : SN54AS21	
SN74AS21	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54AS21 MIN NOM MAX		1	S	1	UNIT	
				MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-2			-2	mA
IOL	Low-level output current			20			20	mA
ТА	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	7507.0	TEST CONDITIONS				S	N74AS2 [,]	1	UNIT
PARAMETER	TESTC	ONDITIONS	MIN T	түр‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	I _I = -18 mA			-1.2			-1.2	V
VOH	V _{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} –2			V _{CC} -2	2		V
VOL	V _{CC} = 4.5 V,	I _{OL} = 20 mA		0.35	0.5		0.35	0.5	V
lj	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
ΙΗ	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
۱ _{IL}	V _{CC} = 5.5 V,	$V_{ } = 0.4 V$			-0.5			-0.5	mA
۱ _O §	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
ICCH	V _{CC} = 5.5 V,	V _I = 4.5 V		2.9	4.6		2.9	4.6	mA
ICCL	V _{CC} = 5.5 V,	V _I = 0		7.4	12		7.4	12	mA

[‡] All typical values are at V_{CC} = 5 V, T_A = 25° C.

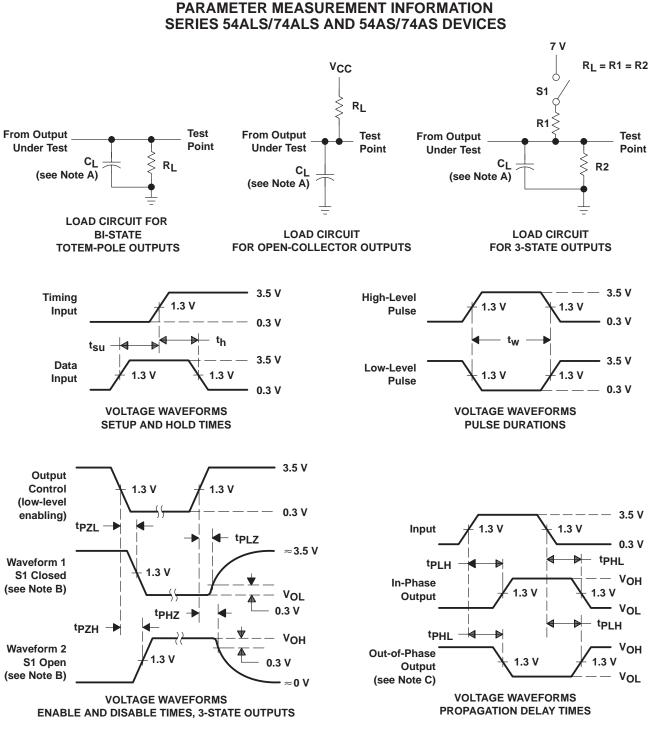
§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	то (оитрит)	CL RL TA	= 50 pF = 500 Ω = MIN t	<u>),</u> o MAX¶		UNIT
			SN54AS21		SN74AS21		
			MIN	MAX	MIN	MAX	
^t PLH	A, B, C, or D	v	1	6.5	1	6	ns
^t PHL	X, B, C, 6 D	1	1	6.5	1	6	115

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

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NOTES: A. C₁ includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- . when measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{f} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-87804012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	
5962-8780401CA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
5962-8780401DA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	
84143012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8414301CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
8414301DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SN54ALS21AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN54AS21J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	
SN74ALS21AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS21ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS21ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS21ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS21ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS21ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS21AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS21ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74ALS21ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS21ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74ALS21ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS21D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS21DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	



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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74AS21DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS21DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS21DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS21DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS21N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS21NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74AS21NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS21NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AS21NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54ALS21AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54ALS21AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54ALS21AW	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)



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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54ALS21A, SN54AS21, SN74ALS21A, SN74AS21 :

• Catalog: SN74ALS21A, SN74AS21

• Military: SN54ALS21A, SN54AS21

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION

REEL DIMENSIONS

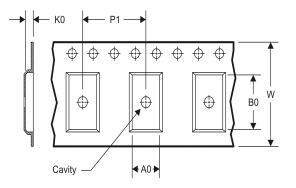
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TAPE AND REEL INFORMATION

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS21ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS21ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS21DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS21NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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PACKAGE MATERIALS INFORMATION

14-Jul-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS21ADR	SOIC	D	14	2500	367.0	367.0	38.0
SN74ALS21ANSR	SO	NS	14	2000	367.0	367.0	38.0
SN74AS21DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74AS21NSR	SO	NS	14	2000	367.0	367.0	38.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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